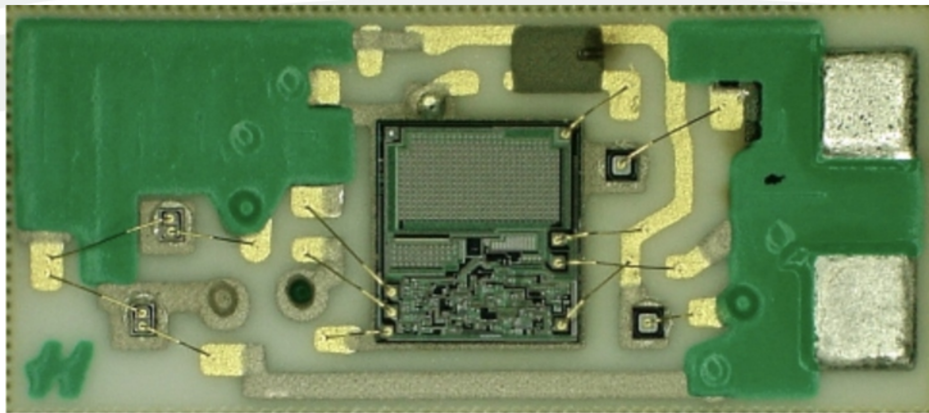
WIRE BONDING

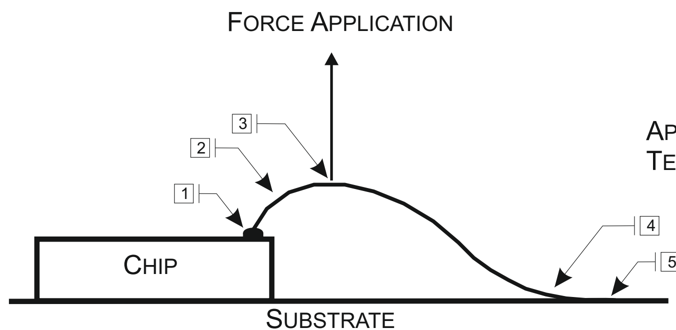
HYBRID SA IS ABLE TO WIRE BOND THE BARE CHIPS. SPECIFIC KNOWLEDGE OF TRAINED PERSONAL AND MODERN MACHINERY ALLOWS THE EXECUTION OF COMPLEX AND HIGH DENSITY BONDING PLAN.(CHIP TO CHIP, CHIP ON CHIP, ETC...)

GOLD WIRE BONDING (BALL BONDING)

DIAMETER : STANDARD 20µm - 30µm



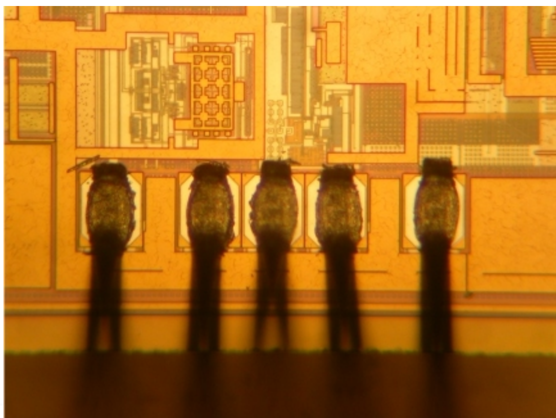
PULL TEST

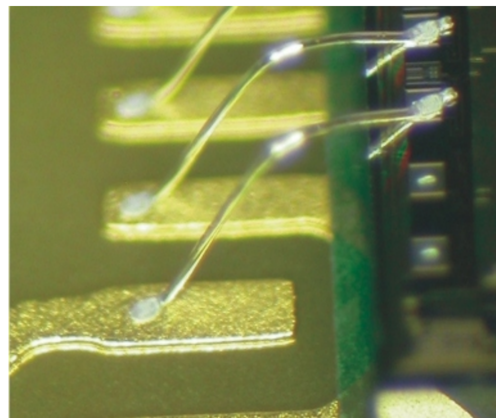


APPLICATION OF THE FORCE UNTIL WIRE FAILURE.
TEST TRACEABILITY.

ALUMINIUM WIRE BONDING (WEDGE BONDING)

DIAMETER : STANDARD 25µm - 33µm





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